

### Features

- High Blocking Voltage with Low On-Resistance
- High Speed Switching with Low Capacitances
- Easy to Parallel and Simple to Drive
- Resistant to Latch-Up
- Halogen Free, RoHS Compliant

### Benefits

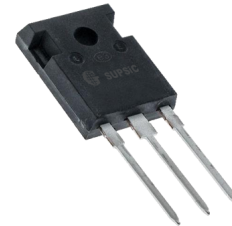
- Higher System Efficiency
- Reduced Cooling Requirements
- Increased Power Density
- Increased System Switching Frequency

### Applications

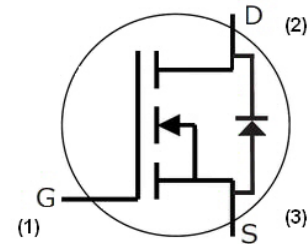
- Solar Inverters
- Switch Mode Power Supplies
- High Voltage DC/DC converters
- Battery Chargers
- Motor Drives
- Pulsed Power Applications

| Part Number  | Package  |
|--------------|----------|
| GC2M0040120D | TO-247-3 |

|                          |               |
|--------------------------|---------------|
| $V_{DS}$                 | 1200 V        |
| $I_D @ 25^\circ\text{C}$ | 55 A          |
| $R_{DS(on)}$             | 40 m $\Omega$ |



TO-247-3  
Package



### Maximum Ratings ( $T_C = 25^\circ\text{C}$ unless otherwise specified)

| Symbol         | Parameter                                  | Value       | Unit             | Test Conditions                                   | Note    |
|----------------|--------------------------------------------|-------------|------------------|---------------------------------------------------|---------|
| $V_{DSmax}$    | Drain - Source Voltage                     | 1200        | V                | $V_{GS} = 0\text{ V}, I_b = 100\ \mu\text{A}$     |         |
| $V_{GSmax}$    | Gate - Source Voltage                      | -10/+25     | V                | Absolute maximum values                           |         |
| $V_{GSop}$     | Gate - Source Voltage                      | -5/+20      | V                | Recommended operational values                    |         |
| $I_D$          | Continuous Drain Current                   | 55          | A                | $V_{GS} = 20\text{ V}, T_C = 25^\circ\text{C}$    | Fig. 19 |
|                |                                            | 36          |                  | $V_{GS} = 20\text{ V}, T_C = 100^\circ\text{C}$   |         |
| $I_{D(pulse)}$ | Pulsed Drain Current                       | 160         | A                | Pulse width $t_p$ limited by $T_{jmax}$           | Fig. 22 |
| $P_D$          | Power Dissipation                          | 278         | W                | $T_C = 25^\circ\text{C}, T_J = 150^\circ\text{C}$ | Fig. 20 |
| $T_J, T_{stg}$ | Operating Junction and Storage Temperature | -55 to +150 | $^\circ\text{C}$ |                                                   |         |
| $T_L$          | Solder Temperature                         | 260         | $^\circ\text{C}$ | 1.6mm (0.063") from case for 10s                  |         |
| $M_d$          | Mounting Torque                            | 1           | Nm<br>lbf-in     | M3 or 6-32 screw                                  |         |
|                |                                            | 8.8         |                  |                                                   |         |

**Electrical Characteristics** ( $T_c = 25^\circ\text{C}$  unless otherwise specified)

| Symbol        | Parameter                                      | Min. | Typ. | Max. | Unit          | Test Conditions                                                                                                                                                                  | Note       |
|---------------|------------------------------------------------|------|------|------|---------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------|
| $V_{(BR)DSS}$ | Drain-Source Breakdown Voltage                 | 1200 |      |      | V             | $V_{GS} = 0\text{ V}, I_D = 100\ \mu\text{A}$                                                                                                                                    |            |
| $V_{GS(th)}$  | Gate Threshold Voltage                         | 2.0  | 3.2  | 4    | V             | $V_{DS} = V_{GS}, I_D = 10\text{mA}$                                                                                                                                             | Fig. 11    |
|               |                                                |      | 2.4  |      | V             | $V_{DS} = V_{GS}, I_D = 10\text{mA}, T_J = 150^\circ\text{C}$                                                                                                                    |            |
| $I_{DSS}$     | Zero Gate Voltage Drain Current                |      | 1    | 100  | $\mu\text{A}$ | $V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}$                                                                                                                                    |            |
| $I_{GSS}$     | Gate-Source Leakage Current                    |      |      | 250  | nA            | $V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$                                                                                                                                      |            |
| $R_{DS(on)}$  | Drain-Source On-State Resistance               |      | 44   | 52   | m $\Omega$    | $V_{GS} = 20\text{ V}, I_D = 40\text{ A}$                                                                                                                                        | Fig. 4,5,6 |
|               |                                                |      | 82   |      |               | $V_{GS} = 20\text{ V}, I_D = 40\text{ A}, T_J = 150^\circ\text{C}$                                                                                                               |            |
| $g_{fs}$      | Transconductance                               |      | 18.2 |      | S             | $V_{DS} = 20\text{ V}, I_{DS} = 40\text{ A}$                                                                                                                                     | Fig. 7     |
|               |                                                |      | 17.2 |      |               | $V_{DS} = 20\text{ V}, I_{DS} = 40\text{ A}, T_J = 150^\circ\text{C}$                                                                                                            |            |
| $C_{iss}$     | Input Capacitance                              |      | 2440 |      | pF            | $V_{GS} = 0\text{ V}$<br>$V_{DS} = 1000\text{ V}$<br>$f = 1\text{ MHz}$                                                                                                          | Fig. 17,18 |
| $C_{oss}$     | Output Capacitance                             |      | 171  |      |               |                                                                                                                                                                                  |            |
| $C_{rss}$     | Reverse Transfer Capacitance                   |      | 11   |      |               |                                                                                                                                                                                  |            |
| $E_{oss}$     | $C_{oss}$ Stored Energy                        |      | 89   |      | $\mu\text{J}$ | $V_{AC} = 25\text{ mV}$                                                                                                                                                          | Fig 16     |
| $E_{ON}$      | Turn-On Switching Energy (Body Diode)          |      | 1.7  |      | mJ            | $V_{DS} = 800\text{ V}, V_{GS} = -5/20\text{ V}$<br>$I_D = 40\text{ A}, R_{G(ext)} = 2.5\ \Omega, L = 99\ \mu\text{H}$                                                           | Fig. 25    |
| $E_{OFF}$     | Turn Off Switching Energy (Body Diode)         |      | 0.4  |      |               |                                                                                                                                                                                  |            |
| $E_{ON}$      | Turn-On Switching Energy (External SiC Diode)  |      | 1.3  |      |               | $V_{DS} = 800\text{ V}, V_{GS} = -5/20\text{ V}$<br>$I_D = 40\text{ A}, R_{G(ext)} = 2.5\ \Omega, L = 99\ \mu\text{H}$                                                           |            |
| $E_{OFF}$     | Turn Off Switching Energy (External SiC Diode) |      | 0.4  |      |               |                                                                                                                                                                                  |            |
| $t_{d(on)}$   | Turn-On Delay Time                             |      | 13   |      | ns            | $V_{DD} = 800\text{ V}, V_{GS} = -5/20\text{ V}$<br>$I_D = 40\text{ A}$<br>$R_{G(ext)} = 2.5\ \Omega, R_L = 20\ \Omega$<br>Timing relative to $V_{DS}$<br>Per IEC60747-8-4 pg 83 | Fig. 27    |
| $t_r$         | Rise Time                                      |      | 61   |      |               |                                                                                                                                                                                  |            |
| $t_{d(off)}$  | Turn-Off Delay Time                            |      | 25   |      |               |                                                                                                                                                                                  |            |
| $t_f$         | Fall Time                                      |      | 13   |      |               |                                                                                                                                                                                  |            |
| $R_{G(int)}$  | Internal Gate Resistance                       |      | 1.8  |      | $\Omega$      | $f = 1\text{ MHz}, V_{AC} = 25\text{ mV}$                                                                                                                                        |            |
| $Q_{gs}$      | Gate to Source Charge                          |      | 34   |      | nC            | $V_{DS} = 800\text{ V}, V_{GS} = -5/20\text{ V}$<br>$I_D = 40\text{ A}$<br>Per IEC60747-8-4 pg 21                                                                                | Fig. 12    |
| $Q_{gd}$      | Gate to Drain Charge                           |      | 42   |      |               |                                                                                                                                                                                  |            |
| $Q_g$         | Total Gate Charge                              |      | 120  |      |               |                                                                                                                                                                                  |            |

### Reverse Diode Characteristics

| Symbol        | Parameter                        | Typ. | Max. | Unit | Test Conditions                                                                                                                             | Note          |
|---------------|----------------------------------|------|------|------|---------------------------------------------------------------------------------------------------------------------------------------------|---------------|
| $V_{SD}$      | Diode Forward Voltage            | 4.0  |      | V    | $V_{GS} = -5\text{ V}, I_{SD} = 20\text{ A}, T_J = 25\text{ }^\circ\text{C}$                                                                | Fig. 8, 9, 10 |
|               |                                  | 3.6  |      | V    | $V_{GS} = -5\text{ V}, I_{SD} = 20\text{ A}, T_J = 150\text{ }^\circ\text{C}$                                                               |               |
| $I_S$         | Continuous Diode Forward Current |      | 60   | A    | $T_C = 25\text{ }^\circ\text{C}$                                                                                                            | Note 1        |
| $I_{S,pulse}$ | Diode Pulse Current              |      | 160  | A    | $V_{GS} = -5\text{ V}$ ,<br>Pulse width $t_p$ limited by $T_{jmax}$                                                                         |               |
| $t_{rr}$      | Reverse Recovery Time            | 54   |      | ns   | $V_{GS} = -5\text{ V}, I_{SD} = 40\text{ A}, T_J = 25\text{ }^\circ\text{C}$<br>$VR = 800\text{ V}$<br>$dif/dt = 1000\text{ A}/\mu\text{s}$ | Note 1        |
| $Q_{rr}$      | Reverse Recovery Charge          | 283  |      | nC   |                                                                                                                                             |               |
| $I_{rrm}$     | Peak Reverse Recovery Current    | 15   |      | A    |                                                                                                                                             |               |

Note (1): When using SiC Body Diode the maximum recommended  $V_{GS} = -5\text{V}$

### Thermal Characteristics

| Symbol          | Parameter                                   | Typ. | Max. | Unit                      | Test Conditions | Note    |
|-----------------|---------------------------------------------|------|------|---------------------------|-----------------|---------|
| $R_{\theta JC}$ | Thermal Resistance from Junction to Case    | 0.33 | 0.45 | $^\circ\text{C}/\text{W}$ |                 | Fig. 21 |
| $R_{\theta JA}$ | Thermal Resistance from Junction to Ambient |      | 40   |                           |                 |         |

Typical Performance

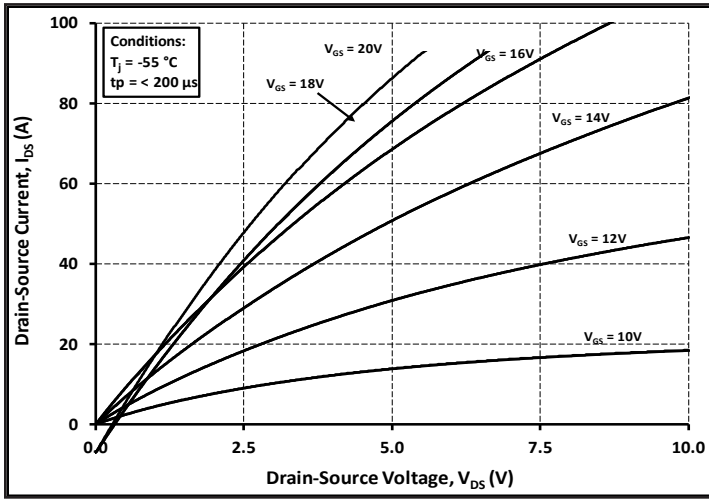


Figure 1. Output Characteristics  $T_J = -55\text{ }^\circ\text{C}$

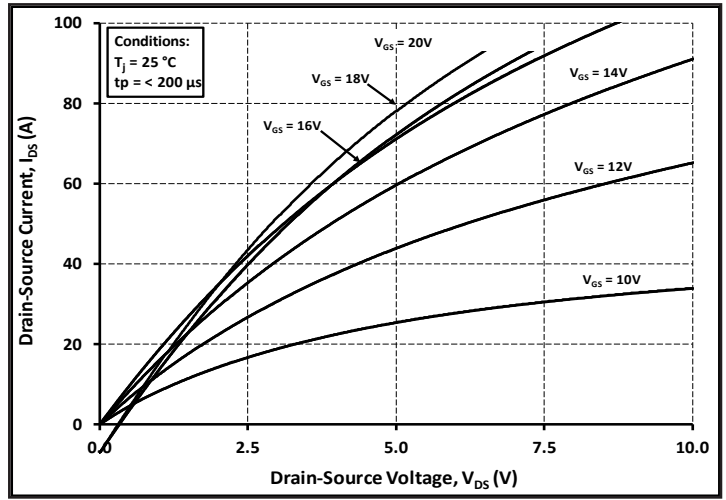


Figure 2. Output Characteristics  $T_J = 25\text{ }^\circ\text{C}$

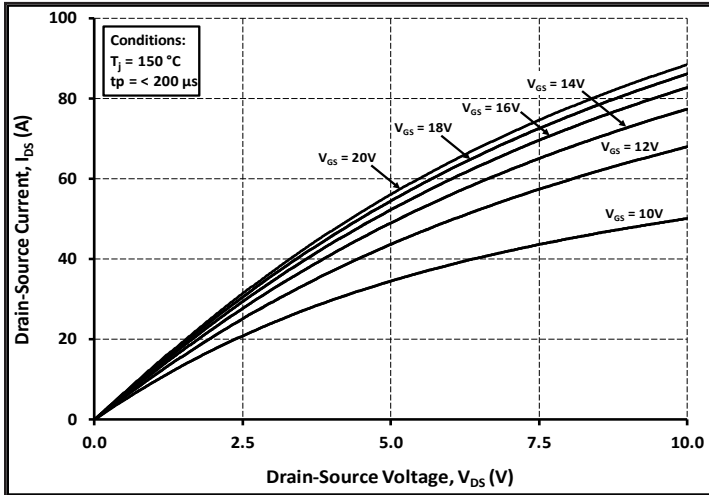


Figure 3. Output Characteristics  $T_J = 150\text{ }^\circ\text{C}$

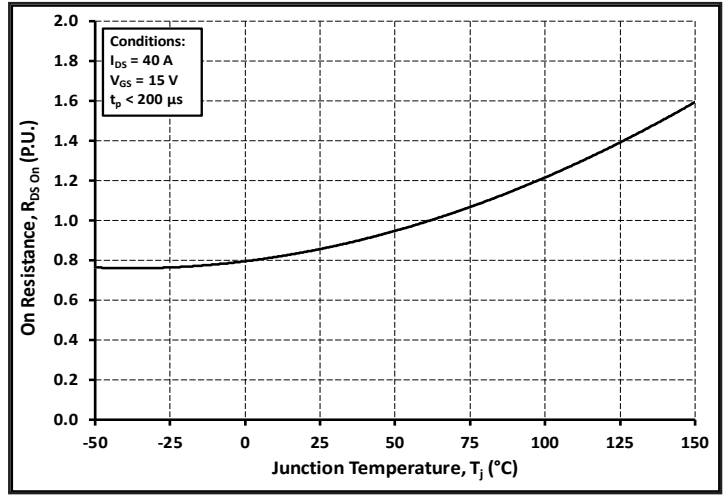


Figure 4. Normalized On-Resistance vs. Temperature

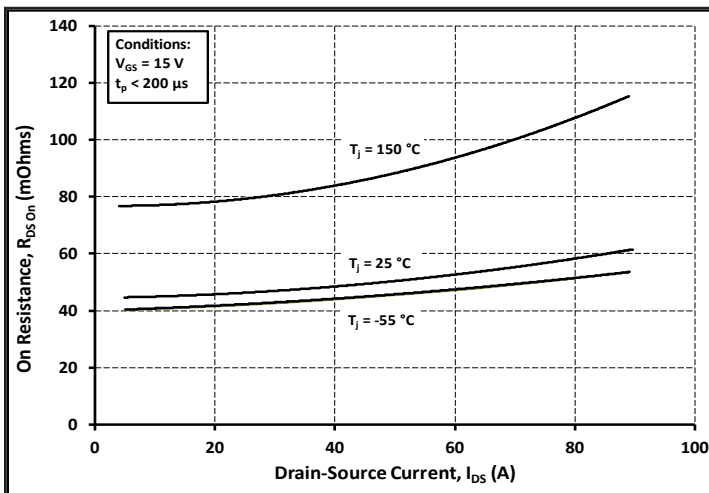


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

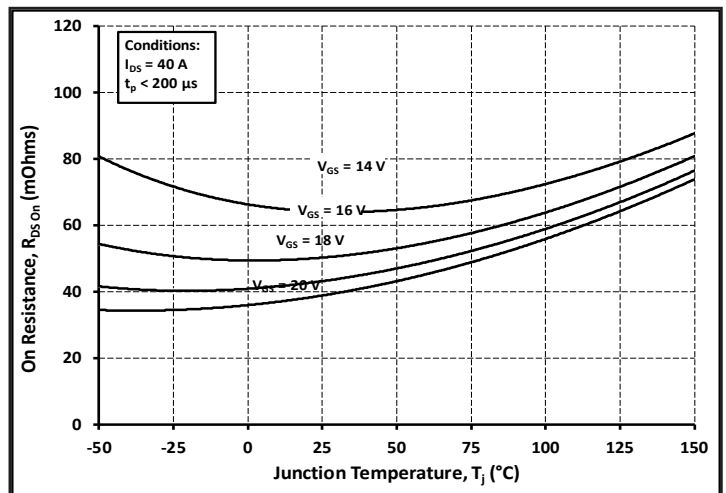


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

Typical Performance

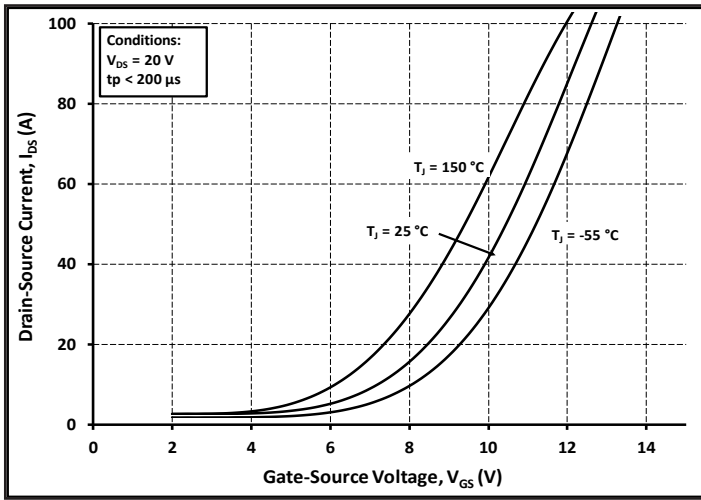


Figure 7. Transfer Characteristic for Various Junction Temperatures

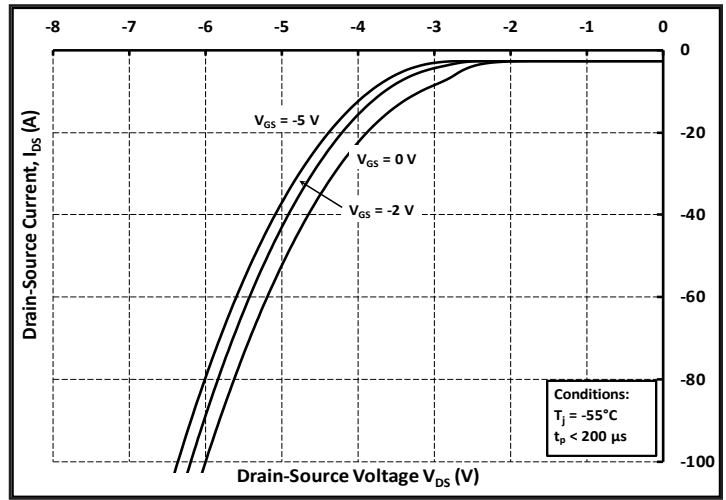


Figure 8. Body Diode Characteristic at -55 °C

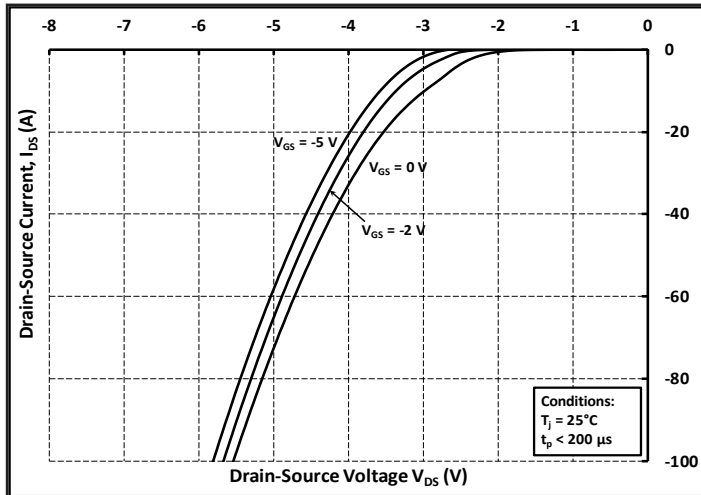


Figure 9. Body Diode Characteristic at 25 °C

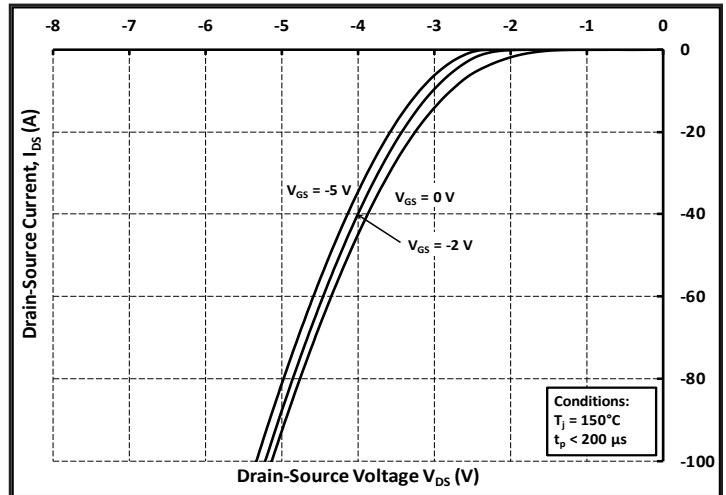


Figure 10. Body Diode Characteristic at 150 °C

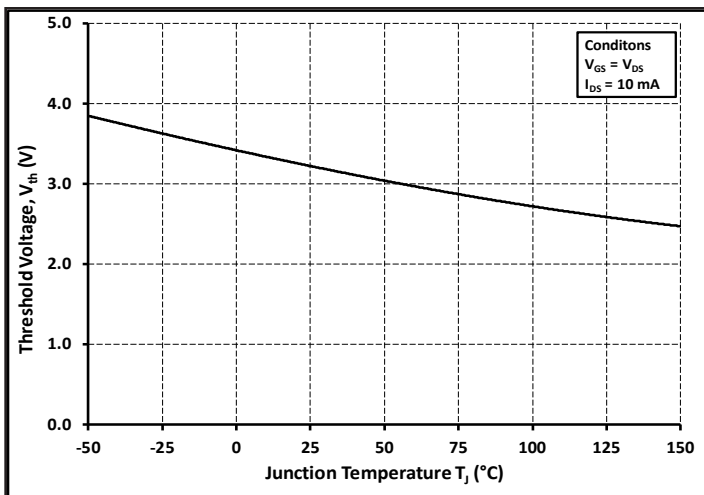


Figure 11. Threshold Voltage vs. Temperature

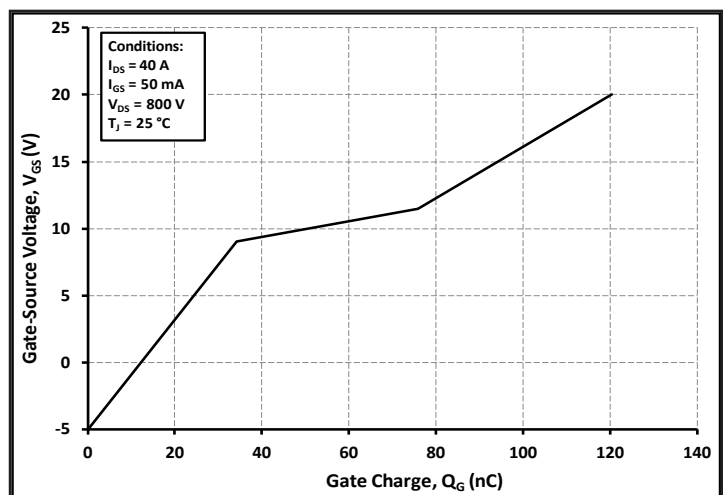


Figure 12. Gate Charge Characteristics

Typical Performance

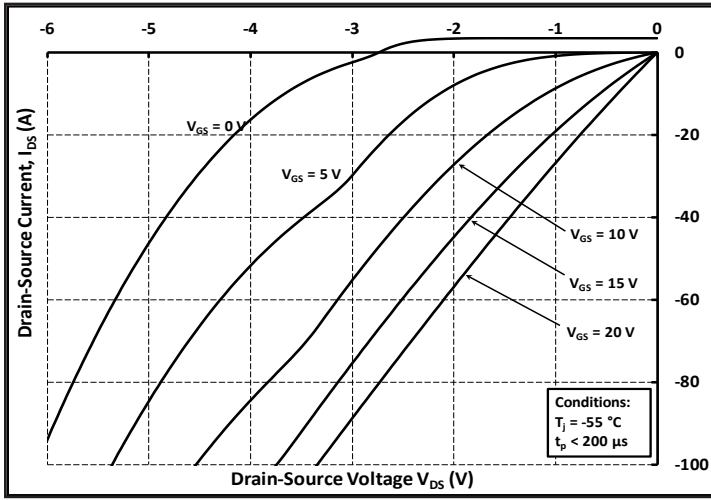


Figure 13. 3rd Quadrant Characteristic at -55 °C

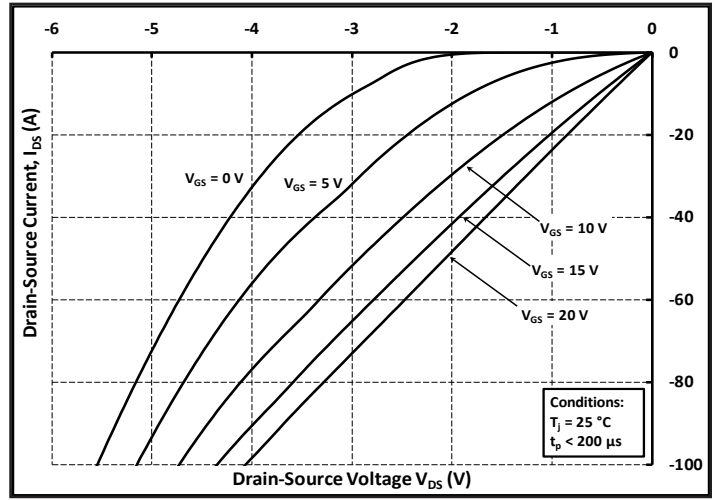


Figure 14. 3rd Quadrant Characteristic at 25 °C

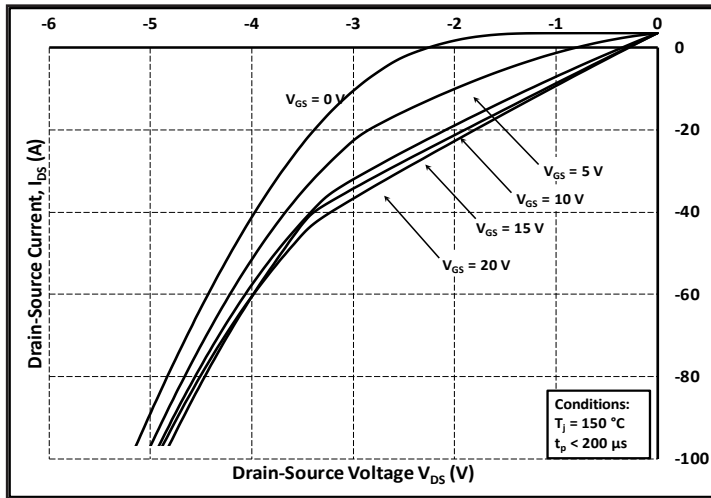


Figure 15. 3rd Quadrant Characteristic at 150 °C

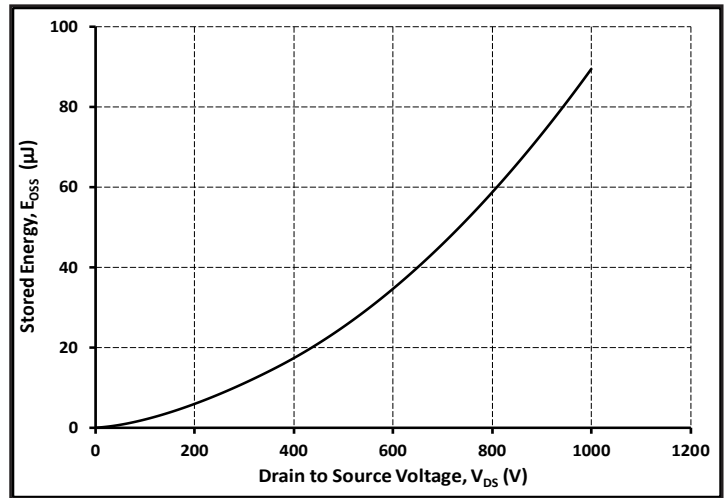


Figure 16. Output Capacitor Stored Energy

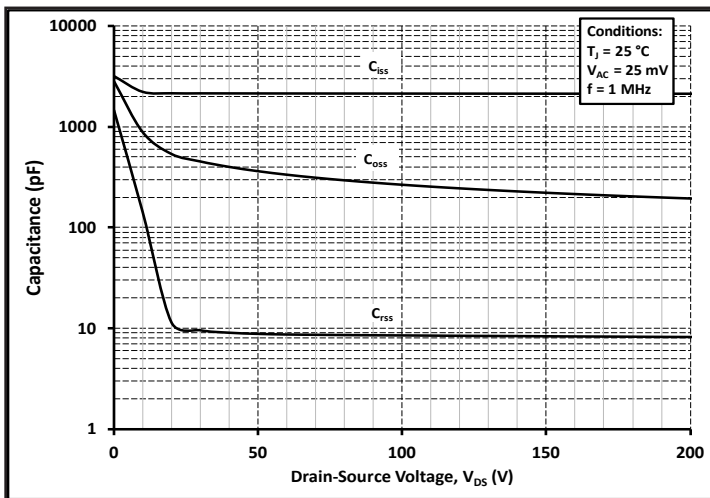


Figure 17. Capacitances vs. Drain-Source Voltage (0-200 V)

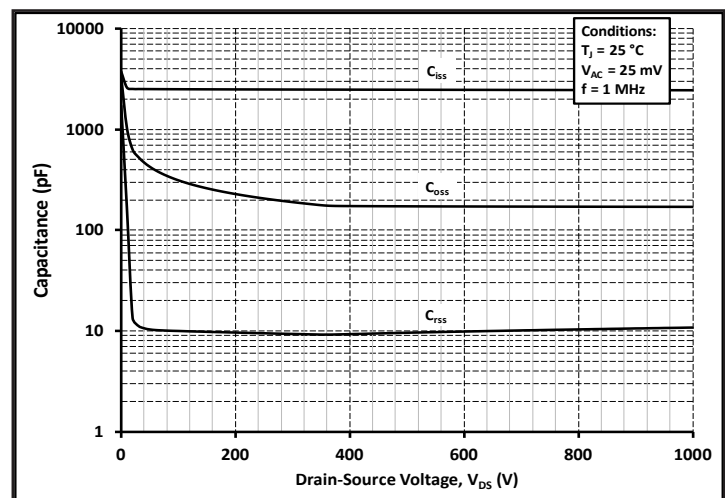


Figure 18. Capacitances vs. Drain-Source Voltage (0-1000 V)

Typical Performance

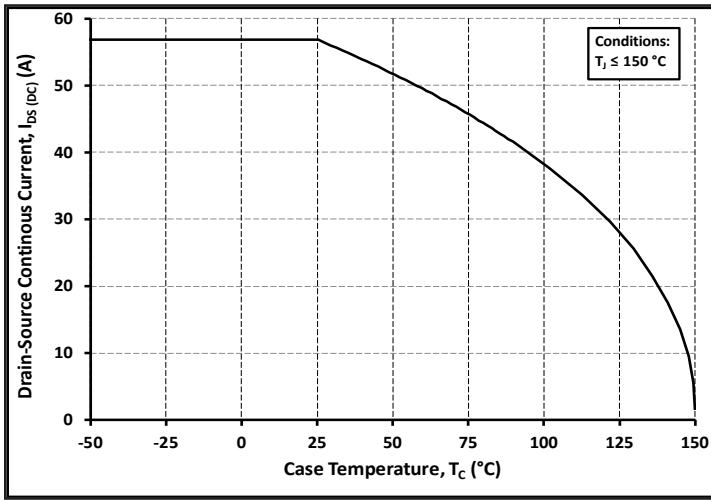


Figure 19. Continuous Drain Current Derating vs. Case Temperature

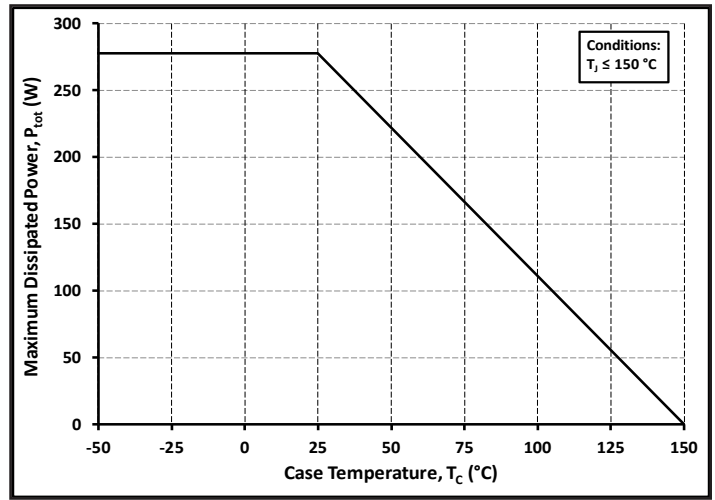


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

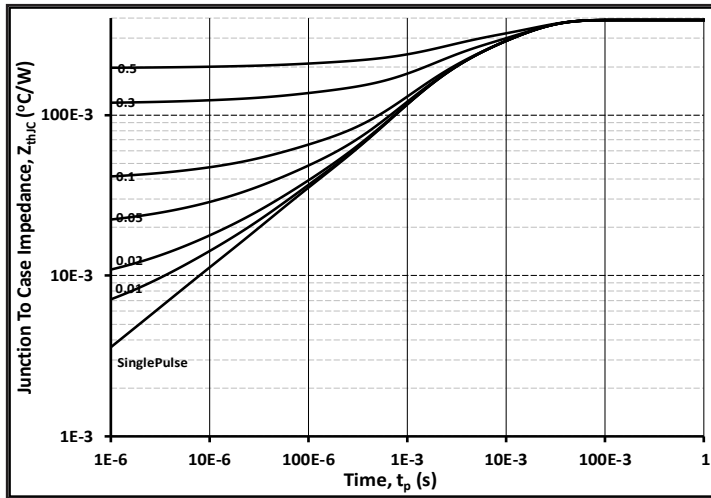


Figure 21. Transient Thermal Impedance (Junction - Case)

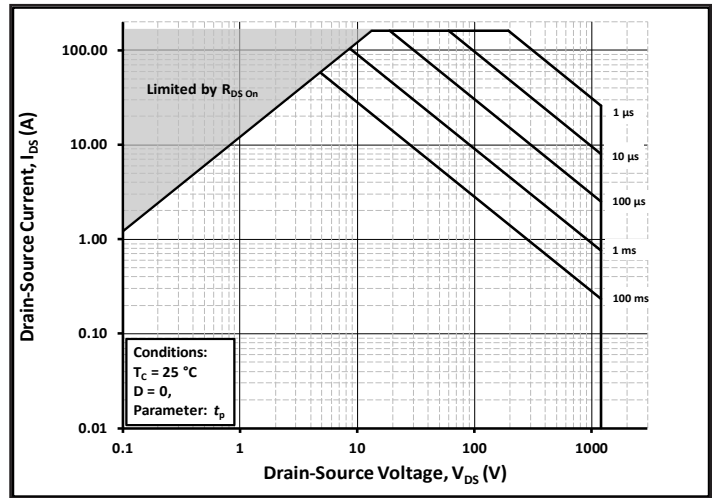


Figure 22. Safe Operating Area

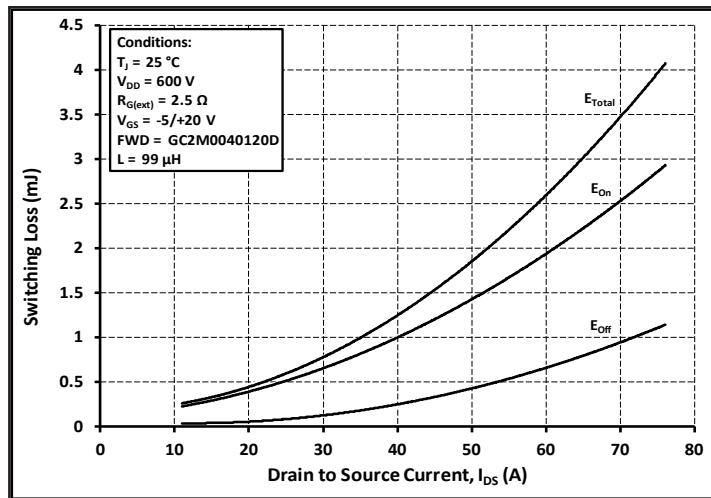


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 600V$ )

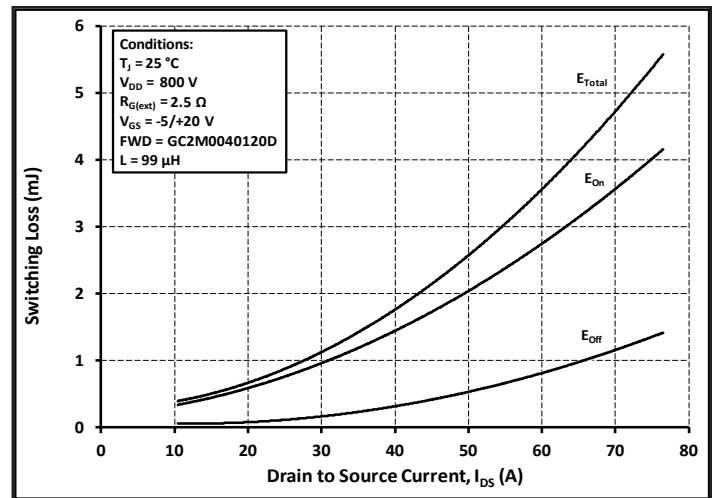


Figure 24. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 800V$ )

Typical Performance

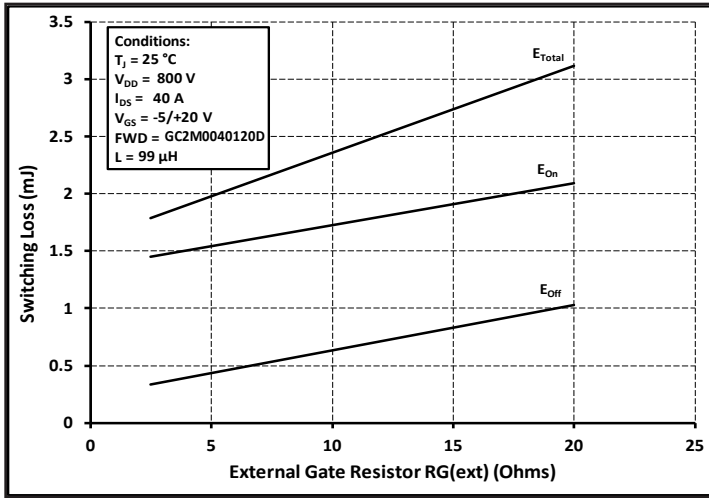


Figure 25. Clamped Inductive Switching Energy vs.  $R_{G(ext)}$

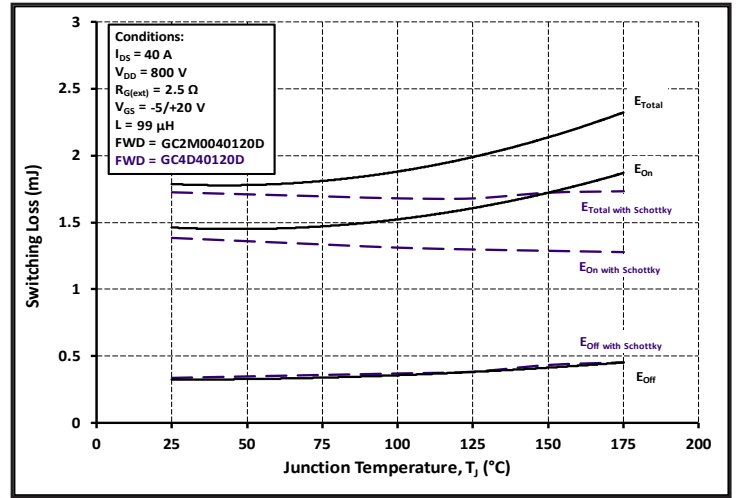


Figure 26. Clamped Inductive Switching Energy vs. Temperature

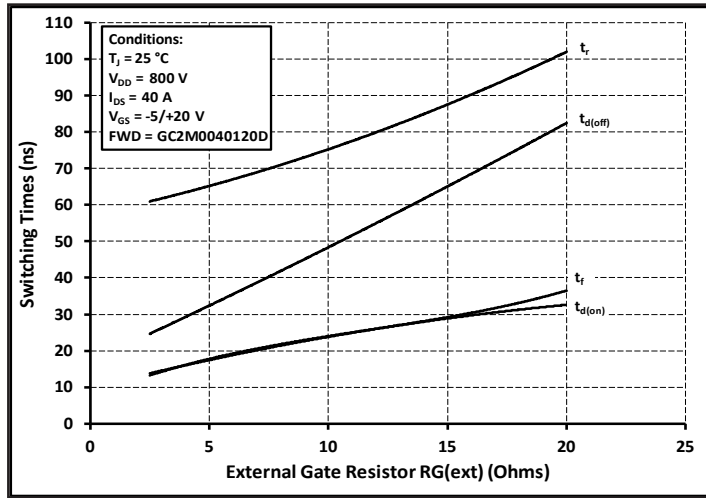


Figure 27. Switching Times vs.  $R_{G(ext)}$

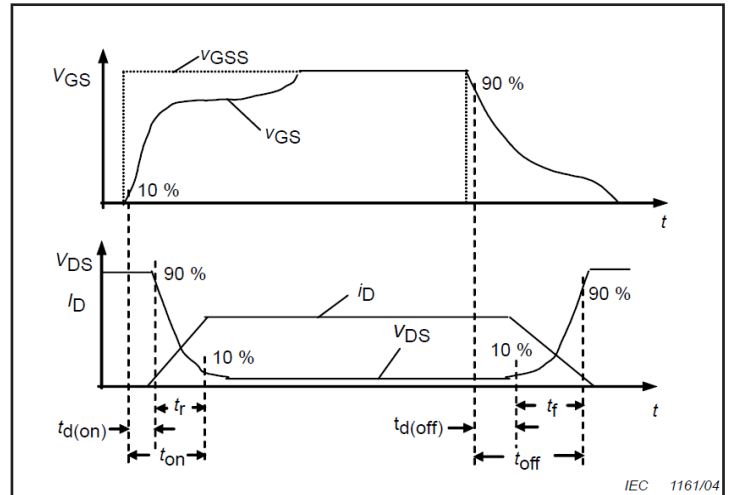


Figure 28. Switching Times Definition



**Test Circuit Schematic**

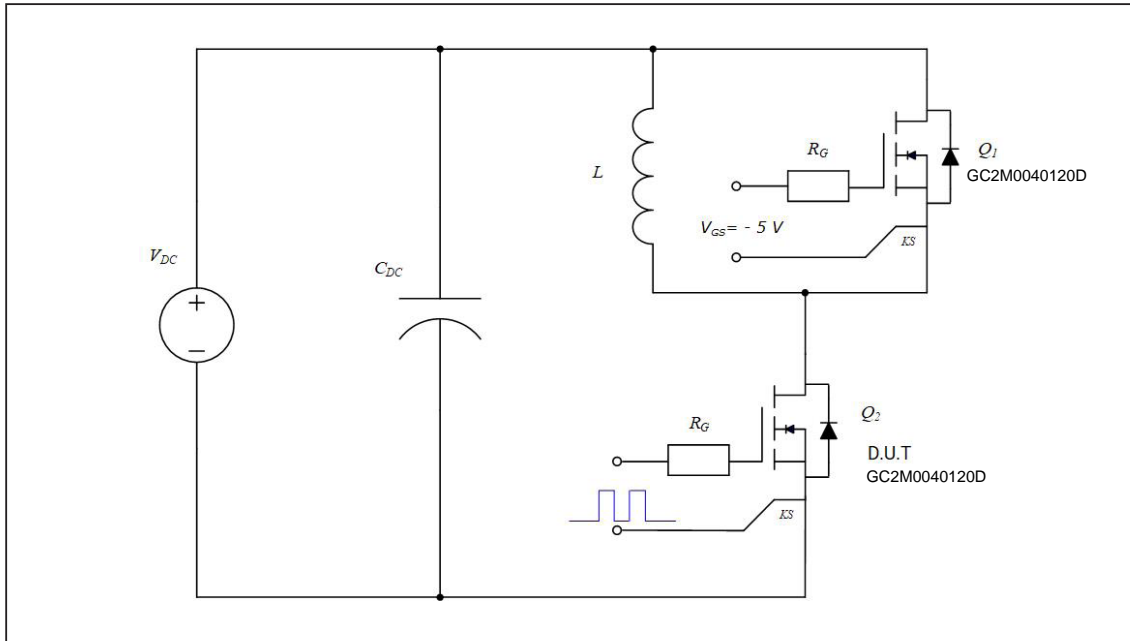


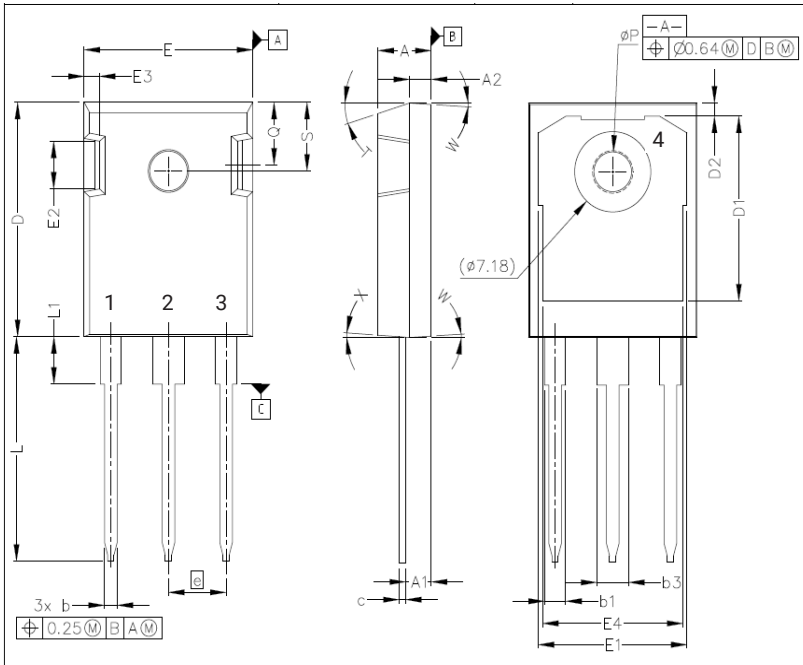
Figure 29. Clamped Inductive Switching  
Waveform Test Circuit

**ESD Ratings**

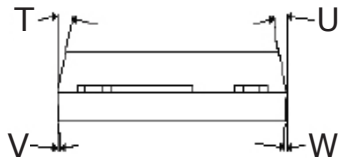
| ESD Test | Resulting Classification |
|----------|--------------------------|
| ESD-HBM  | 3A (4000V - 8000V)       |
| ESD-CDM  | C3 (>=1000V)             |

## Package Dimensions

Package TO-247-3



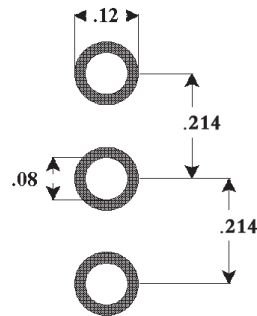
| SYM      | MILLIMETERS |       | INCHES   |      |
|----------|-------------|-------|----------|------|
|          | MIN         | MAX   | MIN      | MAX  |
| A        | 4.83        | 5.21  | .190     | .205 |
| A1       | 2.29        | 2.54  | .090     | .100 |
| A2       | 1.91        | 2.16  | .075     | .085 |
| b        | 1.07        | 1.33  | .042     | .052 |
| b1       | 1.91        | 2.41  | .075     | .095 |
| b3       | 2.87        | 3.38  | .113     | .133 |
| c        | 0.55        | 0.68  | .022     | .027 |
| D        | 20.80       | 21.10 | .819     | .831 |
| D1       | 16.25       | 17.65 | .640     | .695 |
| D2       | 0.95        | 1.25  | .037     | .049 |
| E        | 15.75       | 16.13 | .620     | .635 |
| E1       | 13.10       | 14.15 | .516     | .557 |
| E2       | 3.68        | 5.10  | .145     | .201 |
| E3       | 1.00        | 1.90  | .039     | .075 |
| E4       | 12.38       | 13.43 | .487     | .529 |
| e        | 5.44 BSC    |       | .214 BSC |      |
| N        | 3           |       | 3        |      |
| L        | 19.81       | 20.32 | .780     | .800 |
| L1       | 4.10        | 4.40  | .161     | .173 |
| $\phi P$ | 3.51        | 3.65  | .138     | .144 |
| Q        | 5.49        | 6.00  | .216     | .236 |
| S        | 6.04        | 6.30  | .238     | .248 |
| T        | 17.5° REF.  |       |          |      |
| W        | 3.5° REF.   |       |          |      |
| X        | 4° REF.     |       |          |      |



Pinout Information:

- Pin 1 = Gate
- Pin 2, 4 = Drain
- Pin 3 = Source

## Recommended Solder Pad Layout



TO-247-3

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[IV1B12013HA1L](#) [IV1Q12160T3](#) [IV1Q07015T4G](#) [IV1Q12750O3](#) [IV1Q06040T3](#) [IV1Q12050T4Z](#) [IV1Q12030T4G](#)